Application # 10/646, 478.

1EX7 - E71 100 1		Application 4			- (0 . /	
Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	273	(skip adj via\$1) or (stacked adj via\$1)	EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/06 12:13
L2	1038	(board or substrate) with (via or vias or hole or holes or opening or openings) with (stacked or skip)	EPO; JPO; DERWENT	OR	OFF	2005/01/06 12:20
L3	987	2 not 1	EPO; JPO; DERWENT	OR	OFF	2005/01/06 12:34
S7	609	stacked adj via	US-PGPUB; USPAT	OR	OFF	2005/01/06 12:12
S8	12	skip adj via	US-PGPUB; USPAT	OR	OFF	2005/01/06 12:11
S11	130359	via with via with interface\$1	US-PGPUB; USPAT	OR	OFF	2005/01/04 16:08
S12	641	via near3 via near3 interface\$1	US-PGPUB; USPAT	OR	OFF ·	2005/01/04 16:03
S13	640	S12 not S7	US-PGPUB; USPAT	OR	OFF	2005/01/04 16:06
S14	15	S13 and (crack\$4 or delaminat\$4)	US-PGPUB; USPAT	OR	OFF	2005/01/04 16:05
S16	322	S11 and (stacked and skip)	US-PGPUB; USPAT	OR	OFF	2005/01/04 16:06
S17	322	S16 not S7	US-PGPUB; USPAT	OR	OFF	2005/01/04 16:06
S18	2603	(board or substrate) with (via or vias or hole or holes or opening or openings) with (stacked or skip)	US-PGPUB; USPAT	OR	OFF	2005/01/04 16:10
S19	1644	(board or substrate) with (via or vias or hole or holes or opening or openings) with (stacked or skip)	USPAT	OR	OFF	2005/01/06 12:20
S20	1564	S19 not S7	USPAT	OR	OFF	2005/01/04 16:35